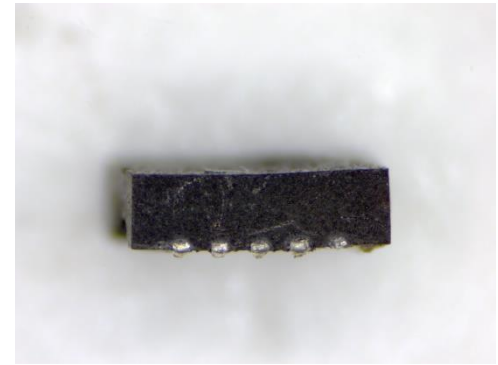
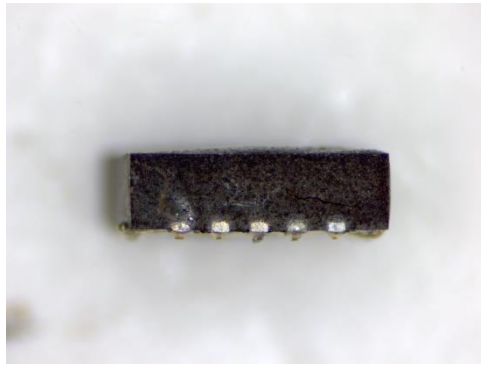
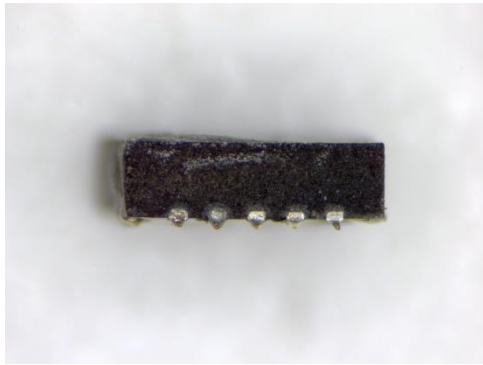
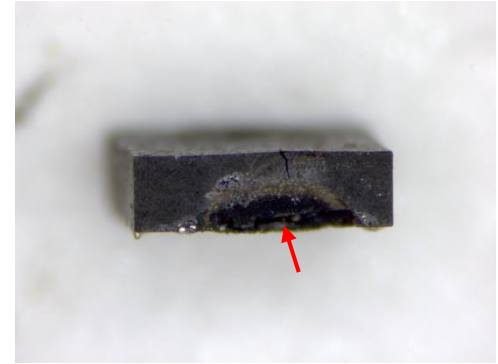
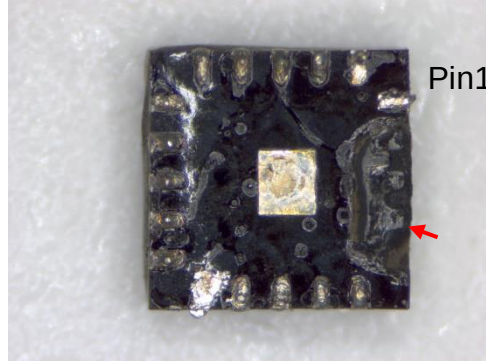
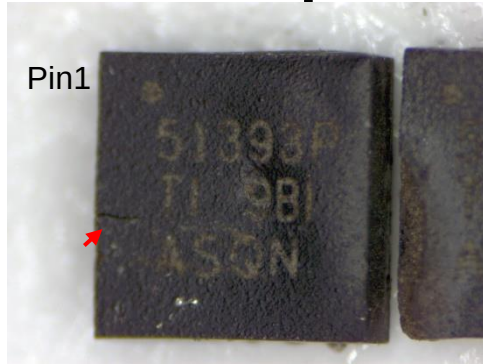
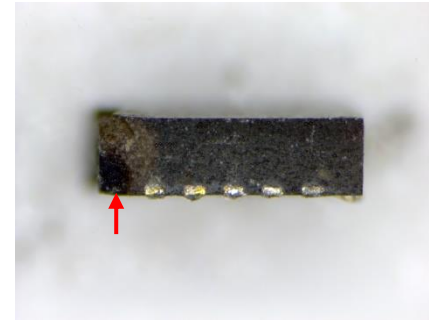
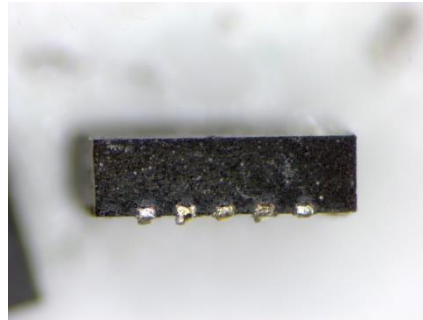
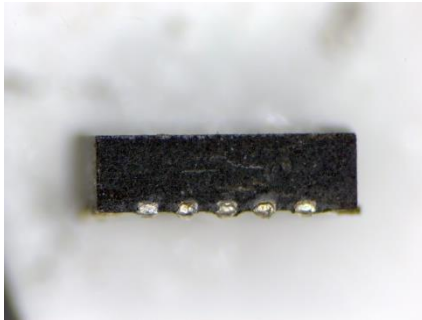
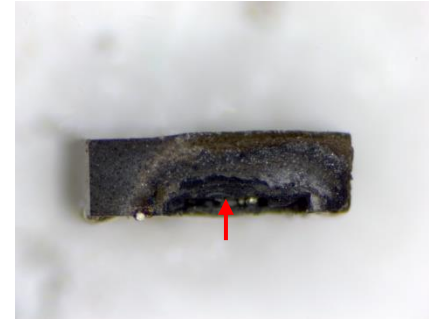
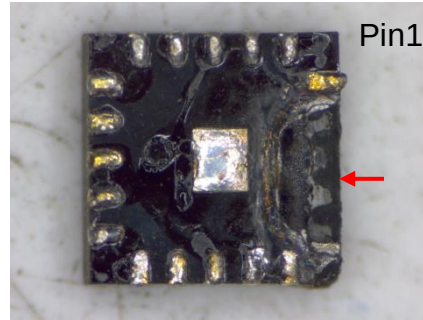
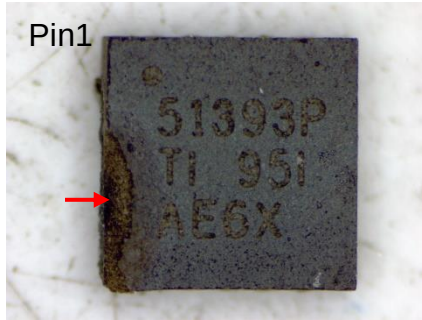


Optical inspection for #1



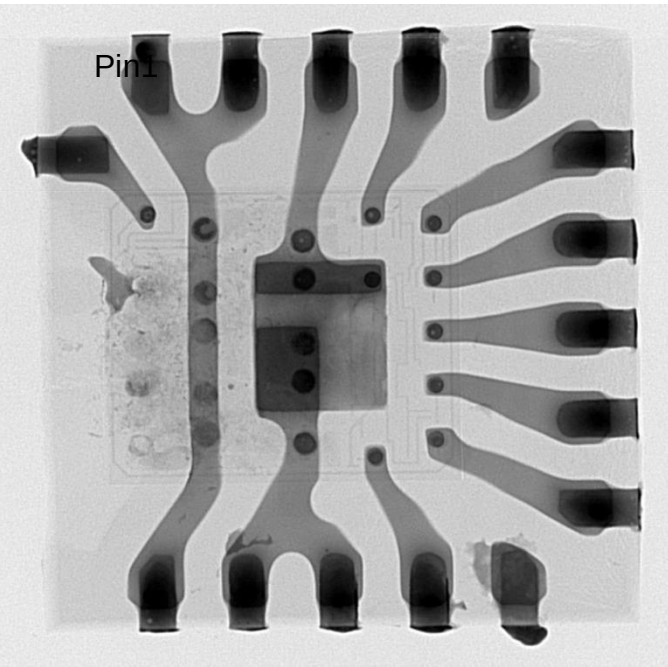
Unit#1: burnt mark was observed at pin1-pin5 area

Optical inspection for #2

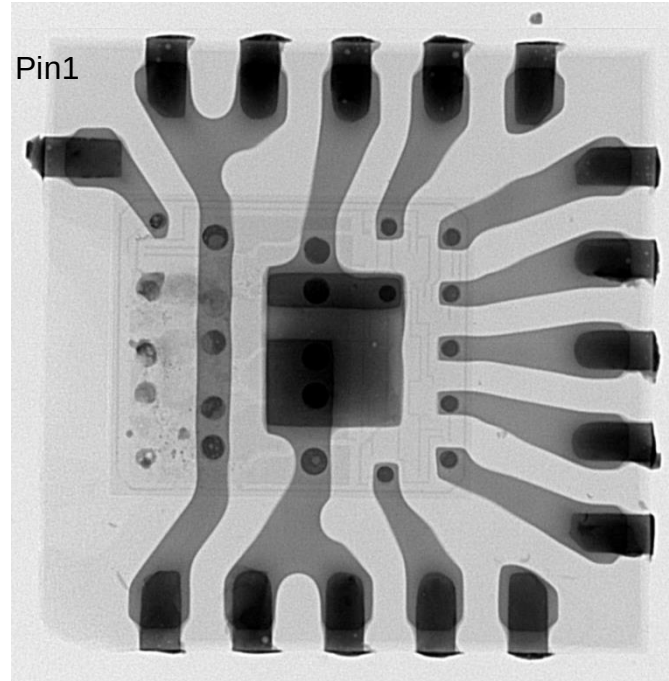


Unit#2: burnt mark was observed at pin1-pin5 area

X-ray inspection for units (#1-#2)



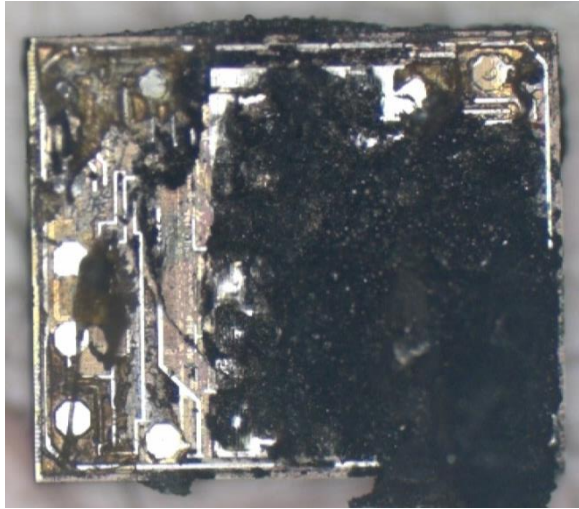
Unit#1



Unit#2

Fused solder joints was observed at pin1-pin6, pin19-pin20 area on both units

Decapsulation

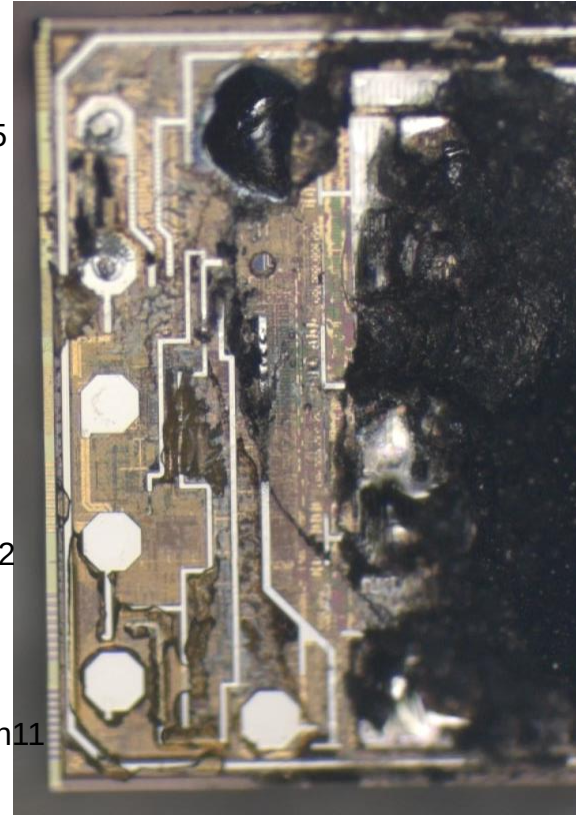


Pin1

Pin15

Pin12

Pin11



Unit#1: Sever EOS damage over die
no damage was observed at pin11-pin13.